

Reliability Test Summary

No	Test Item	Test Condition	Test Foundation	Quality Level
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5℃ Time= 5~10 sec.	MIL-STD-750 Method 2026	Ac/Rj=22/0
2	Soldering Heat	Temp of solder pot=260±5℃ Time= 10~12 sec	MIL-STD-750 Method 2031	Ac/Rj=22/0
3	Temperature Cycle	Low Tstg to High Tstg dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750 Method 1051	Ac/Rj=22/0
4	Steady State Operation Life Test	I=Io mA Time=168hrs.	MIL-STD-750 Method 1027	Ac/Rj=22/0
5	High Temperature Reverse Bias Life	VR= VR*80% Ta=TJ MAX. (depend on product) Time 168hrs.	MIL-STD-750 Method 1038	Ac/Rj=22/0
6	Intermittent Forward Operation Life	If = Io mA ON 1.5hrs/OFF 0.5hrs Test Time : 84Cycles	MIL-STD-750 Method 1036	Ac/Rj=22/0
7	Pressure Cooker Test	Ta= 121℃ Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	Ac/Rj=22/0
8	High Temperature Storage Life	Ta= TSTG MAX. Time= 168 hrs	MIL-STD-750 Method 1031	Ac/Rj=22/0
9	Humidity	Ta= 85 °C RH= 85% Time=168 hrs	EIAJ ED-4701	Ac/Rj=22/0